



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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JUL 25 2003  
TECHNOLOGY CENTER 2800

In re the Application of:

Heinen, et al.

Docket No.: TI-23158

Serial No.: 09/186,973

Examiner: Foong, S.

Filed: 11/05/98

Art Unit: 2823

For: Wafer-scale Assembly of Chip-size Packages

Amendment under 37 CFR 1.111

Commissioner of Patents

P.O. Box 1450

Alexandria, VA, 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on 7-14-03



Michael K. Skrehot, Reg. No. 36,682

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 3/14/03. They are respectfully submitted as a full and complete response to that Action. A petition for a one-month extension of time accompanies this response. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.